Next-Generation Digital Infrastructure Construction (Amount covered by the government: Up to 141.0 billion yen)

[Next-Generation Green Power Semiconductors]

- Power semiconductors are <u>used to control various electrical products</u> related to everyday life, such as automobiles and industrial equipment, electric power generation and railways, and home appliances. For example, <u>about 20% of the power loss of electric vehicles is</u> said to be <u>caused</u> <u>by power semiconductors</u>. That means they <u>have significant implications for the energy efficiency of various electrical devices</u>.
- This project will work toward <u>reducing the power loss</u> of next-generation power semiconductors (SiC, GaN, etc.) <u>by more than 50%</u> and <u>reducing their cost to achieve similar cost levels to</u> those of Si power semiconductors, in order to promote their social implementation in <u>the fields</u> where innovative improvements in energy efficiency are required toward carbon neutrality, such as electric vehicles, electric power generation (e.g., by renewable energy) and server power supplies.

[Next-Generation Green Data Centers]

- In response to the surge in power consumption by data centers due to social and industrial digitalization, international efforts are ongoing to achieve ultra-low power consumption and ultra-fast processing by introducing photonics-electronics convergence technology.
- This project aims to <u>significantly improve the energy efficiency of data centers</u> (i.e., data aggregation hubs) <u>by over 40%</u> through innovative <u>photonics-electronics convergence</u> <u>technology</u> that replaces electrical wiring inside servers with optical wiring.

<u> Next-generation green-power semiconductors </u>

- In order to **improve performance and reliability**, develop technologies that are closely related to defect rate reduction, and that are closely related to control technologies.
- In order to <u>reduce costs</u>, <u>develop manufacturing technologies to</u> increase the wafers' diameters (from 150 mm to 200 mm) and improve their quality, while also making use of AI.

OExpected approaches (examples)

NB: Assuming SiC for the medium- and large-power ranges and GaN for the small-power range

Medium-power range

Small-power range (For server power supplies, etc.)

High-efficiency, compact power supplies

- -750-V class or lower
- Improved performance and reliability
- High-quality crystal growth technology
- High-efficiency control functions (e.g., measures against electromagnetic noise)
- Developing circuit technology
 (e.g., high-efficiency power sources)

(For xEVs / industrial equipment) Inverters for electric vehicles -1.2-kV class -Improved performance and reliability -High-quality wafers with larger diameters -High-efficiency control functions (e.g., high-efficiency motor drives) Inverters for industrial equipment -1.7-kV class -Improved performance and reliability -High-quality wafers with larger diameters -High power density (e.g., rapid charging) -Module technology (e.g.,

improved heat dissipation)

Large-power range ((Electric power generation such as by renewable energy)

Electric power systems

- -3.3-kV class
- Improved performance and reliability
- High-quality wafers with larger diameters
- -Module technology (e.g., reliability in the event of a failure)
- High breakdown voltage (e.g., high power conversion for grid networks)

O Next-generation green data centers

- <u>Photonics-electronics convergence technology has</u> <u>emerged as a game changer</u> for <u>innovative improvements in</u> <u>the energy efficiency of data centers</u>.
- Photonics-electronics convergence technology <u>combines</u> <u>optoelectronics</u> with electronic devices, replacing electrical wiring with optical wiring. This <u>results in improved energy</u> <u>efficiency, higher capacity, and lower latency (with the</u> <u>power consumption of the entire network system reduced</u> <u>to 1/100</u>).
- O Power consumption of chip-to-chip wiring





